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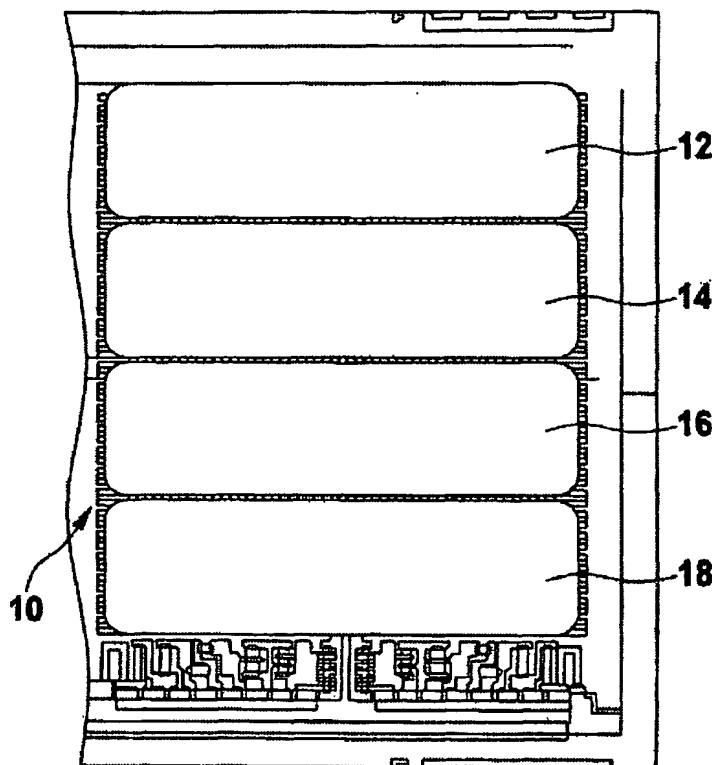
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(54) Title: DISCRETE SEMICONDUCTOR COMPONENT



(57) Abstract: A discrete semiconductor component, and in particular a magnetoresistive sensor, having an active circuit that is provided in an active layer (10) on the surface of a substrate, at least one bond pad (12,14,16,18) that forms a bonding surface for a bond wire (22,24,26,28), and electrical connections (20) between the at least one bond pad and the active circuit, is characterized in that the bond pad or pads (12,14,16,18) is or are arranged above the active layer (10).

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